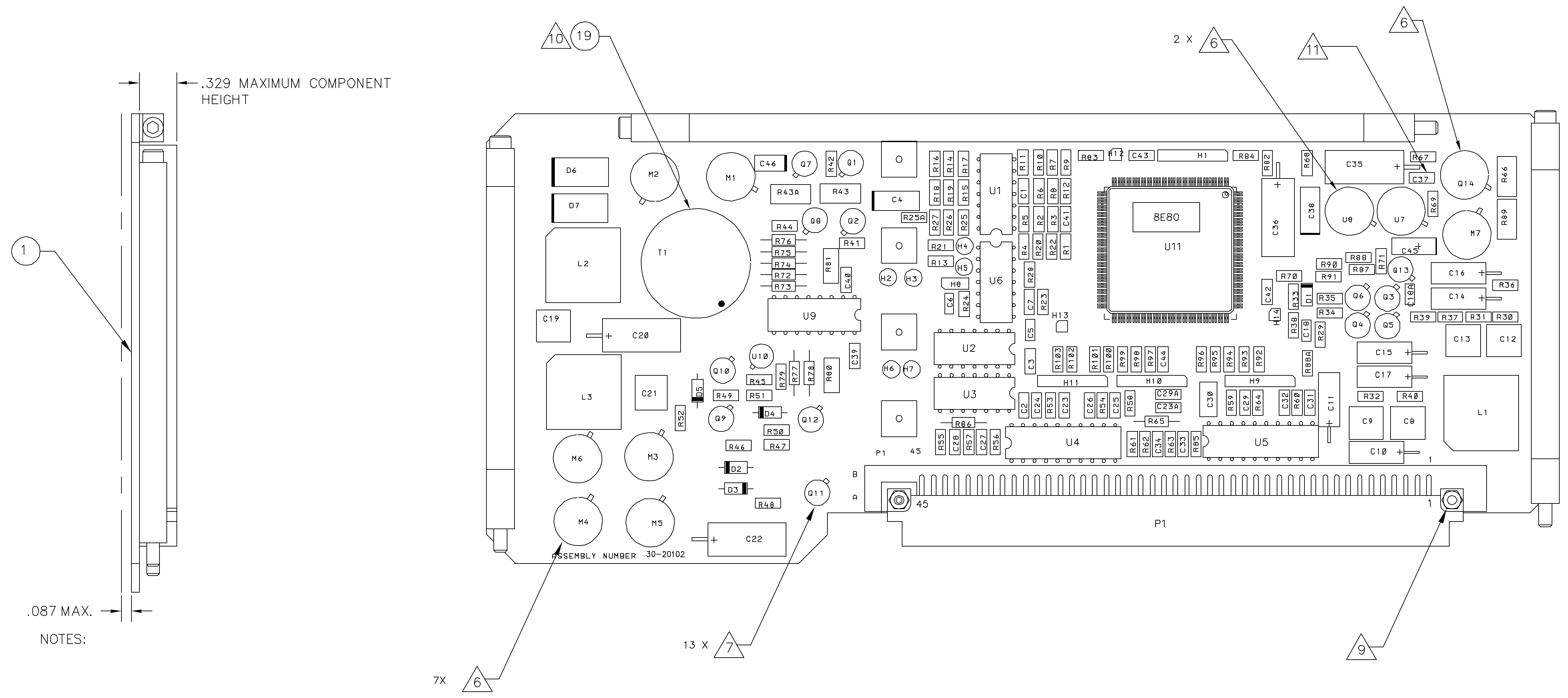


REVISIONS			CHECKED	APPROVED	DATE
30-041	A	INITIAL RELEASE GENERATE SEPERATE ASSY FOR LL	EAB	R. FOSTER	3/21/03
30-071	B	AS BUILT	EAB	R. FOSTER	11/13/03
30-077	C	REDESIGN			



NOTES:

- NOTES:
- SOLDERING TO BE IAW NASA SPECIFICATION NAS-STD-8739.2 AND NAS-STD-8739.3
  - IC PATTERN FOR U11 IS TOO WIDE. LEADS WERE REFORMED AT MIT. CENTER LEADS ON PADS PRIOR TO SOLDERING.
  - ITEM IS STATIC SENSITIVE. HANDLE IAW MIT PROCEDURE 99-01003 OR EQUIVALENT.
  - EVENLY SPACE ALL SMD'S ON PADS PRIOR TO SOLDERING.
  - DO NOT INSTALL TEST HEADERS. (H1-H14)
  - EPOXY ALL FLUSH MOUNTED COMPONENTS Q14, M1-7, AND U7-8 TO THE BOARD USING F/N 18. EPOXY LAYER TO BE AS THIN AS POSSIBLE.
  - SPACE Q1-13 OFF F/N 1 .035"-.05". ENSURE CASE DOES NOT TOUCH ADJACENT COMPONENTS.
  - PARTS TO RECEIVE CURSORY VISUAL INSPECTION PRIOR TO INSTALLATION.
  - ATTACH P1 TO PCB WITH SUPPLIED HARDWARE AND TORQUE TO 32 IN OZ PRIOR TO SOLDERING TO PCB.
  - TORQUE F/N 19, #6-32UNC SCREW TO 80 IN-OZ PRIOR TO SOLDERING.
  - C37 HAS VIA LOCATED UNDERNEATH AND CLOSE TO ONE END. OFFSET C37 TO AVOID SHORTING TO VIA.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCE: ANGLES +/- 1° 3 PLACE DECIMALS +/- .005 2 PLACE DECIMALS +/- .01		NAME	DATE	Massachusetts Institute of Technology Center for Space Research ASTRO-E2
30-20200	ASTRO-E2	DRAWN M. SMITH	3/10/03	
MATERIAL N/A		CHECKED EAB	3/10/03	CCA, THERMAL CONTROL LINCOLN LABS ASSY DRG
FINISH N/A		APPROVED R. FOSTER	3/10/03	
NEXT ASSEMBLY	USED ON	RELEASED D.GAGE	3/10/03	SIZE D
APPLICATION		CAD FILE		FSCM NO. 80230
				DWG NO. 30-20200.97
				SCALE 1:1
				SHEET 1 OF 1